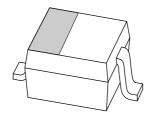
DISCRETE SEMICONDUCTORS

DATA SHEET



BAT760Schottky barrier diode

Product specification Supersedes data of 2001 Mar 12 2004 Jan 26





Schottky barrier diode

BAT760

FEATURES

- Ultra high-speed switching
- Very low forward voltage
- · Guard ring protected
- Very small SMD plastic package.

APPLICATIONS

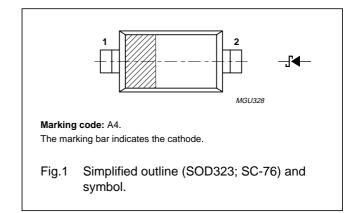
- Ultra high-speed switching
- Voltage clamping
- Protection circuits.

DESCRIPTION

Planar Schottky barrier diode with an integrated guard ring for stress protection in a SOD323 (SC-76) very small SMD plastic package.

PINNING

PIN	DESCRIPTION
1	cathode
2	anode



ORDERING INFORMATION

TYPE		PACKAGE					
NUMBER	NAME	DESCRIPTION	VERSION				
BAT760	_	plastic surface mounted package; 2 leads	SOD323				

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_R	continuous reverse voltage		_	20	V
I _F	continuous forward current		_	1	Α
I _{FSM}	non-repetitive peak forward current	t = 8.3 ms half sinewave; JEDEC method	_	5	А
T _{stg}	storage temperature		-65	+150	°C
Tj	junction temperature		_	125	°C
T _{amb}	operating ambient temperature		-65	+125	°C

Philips Semiconductors Product specification

Schottky barrier diode

BAT760

CHARACTERISTICS

 T_{amb} = 25 °C unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	TYP.	MAX.	UNIT
V _F	continuous forward voltage	see Fig.2 and note 1			
		I _F = 10 mA	240	270	mV
		I _F = 100 mA	300	350	mV
		I _F = 1 A	480	550	mV
I _R	reverse current	see Fig.3 and note 1			
		V _R = 5 V	5	10	μΑ
		V _R = 8 V	7	20	μΑ
		V _R = 15 V	10	50	μΑ
C _d	diode capacitance	$V_R = 5 \text{ V}$; $f = 1 \text{ MHz}$; see Fig.4	19	25	pF

Note

1. Pulse test: t_p = 300 μ s; δ = 0.02.

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
R _{th(j-a)}	thermal resistance from junction to ambient	note 1	220	K/W
		note 2	180	K/W

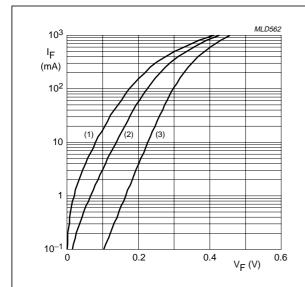
Notes

- 1. Mounted on printed-circuit board $10 \times 10 \text{ mm}^2 \text{ Cu}$.
- 2. Mounted on printed-circuit board $40 \times 40 \text{ mm}^2 \text{ Cu}$.

Schottky barrier diode

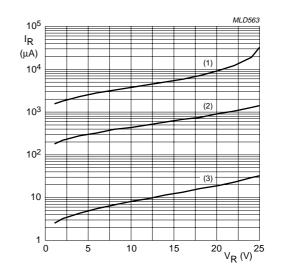
BAT760

GRAPHICAL DATA



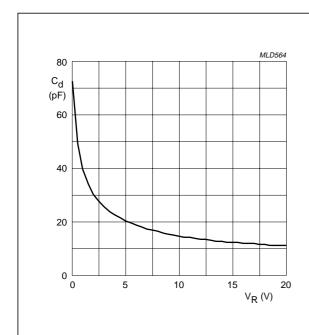
- (1) $T_{amb} = 125 \,^{\circ}C$.
- (2) $T_{amb} = 85 \, ^{\circ}C$.
- (3) $T_{amb} = 25 \, ^{\circ}C$.

Fig.2 Forward current as a function of forward voltage; typical values.



- (1) $T_{amb} = 125 \, ^{\circ}C$.
- (2) $T_{amb} = 85 \, ^{\circ}C$.
- (3) $T_{amb} = 25 \, ^{\circ}C$.

Fig.3 Reverse current as a function of reverse voltage; typical values.



 $T_{amb} = 25 \, ^{\circ}C; f = 1 \, MHz.$

Fig.4 Diode capacitance as a function of reverse voltage; typical values.

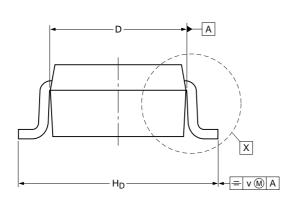
Schottky barrier diode

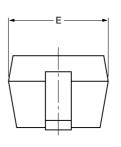
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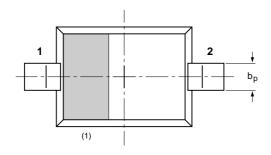
PACKAGE OUTLINE

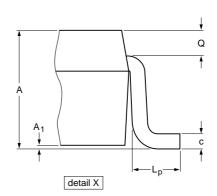
Plastic surface mounted package; 2 leads

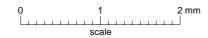
SOD323











DIMENSIONS (mm are the original dimensions)

l	JNIT	Α	A ₁ max	bp	С	D	E	H _D	Lp	Q	v
ı	mm	1.1 0.8	0.05	0.40 0.25	0.25 0.10	1.8 1.6	1.35 1.15	2.7 2.3	0.45 0.15	0.25 0.15	0.2

Note

1. The marking bar indicates the cathode

OUTLINE	REFERENCES				EUROPEAN	ISSUE DATE
VERSION	IEC	JEDEC	JEITA		PROJECTION	ISSUE DATE
SOD323			SC-76			99-09-13 03-12-17

Philips Semiconductors Product specification

Schottky barrier diode

BAT760

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS ⁽¹⁾	PRODUCT STATUS(2)(3)	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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Notes

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- 2. The product status of the device(s) described in this data sheet may have changed since this data sheet was published. The latest information is available on the Internet at URL http://www.semiconductors.philips.com.
- 3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

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Short-form specification — The data in a short-form specification is extracted from a full data sheet with the same type number and title. For detailed information see the relevant data sheet or data handbook.

Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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